TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM739207

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
JPMORGAN CHASE BANK, N.A.		07/06/2022	Association: UNITED STATES

RECEIVING PARTY DATA

Name:	CABOT MICROELECTRONICS CORPORATION
Street Address:	870 N. Commons Dr.
City:	Aurora
State/Country:	ILLINOIS
Postal Code:	60504
Entity Type:	Corporation: DELAWARE
Name:	QED TECHNOLOGIES INTERNATIONAL, INC.
Street Address:	1040 University Avenue
City:	Rochester
State/Country:	NEW YORK
Postal Code:	14607
Entity Type:	Corporation: DELAWARE
Name:	FLOWCHEM LLC
Street Address:	43253 Old Houston Highway
City:	Waller
State/Country:	TEXAS
Postal Code:	77484
Entity Type:	Limited Liability Company: DELAWARE
Name:	KMG ELECTRONIC CHEMICALS, INC.
Street Address:	300 Throckmorton Street
City:	Fort Worth
State/Country:	TEXAS
Postal Code:	76102
Entity Type:	Corporation: TEXAS
Name:	KMG-BERNUTH, INC.
Street Address:	300 Throckmorton Street
City:	Fort Worth

OP $1615.00 4372801

State/Country:	TEXAS
Postal Code:	76102
Entity Type:	Corporation: DELAWARE
Name:	MPOWER SPECIALTY CHEMICALS LLC
Street Address:	43253 Old Houston Highway
City:	Waller
State/Country:	TEXAS
Postal Code:	77484
Entity Type:	Limited Liability Company: TEXAS
Name:	SEALWELD (USA), INC.
Street Address:	300 Throckmorton Street
City:	Fort Worth
State/Country:	TEXAS
Postal Code:	76102
Entity Type:	Corporation: TEXAS
Name:	INTERNATIONAL TEST SOLUTIONS, LLC
Street Address:	870 N. Commons Dr.
City:	Aurora
State/Country:	ILLINOIS
Postal Code:	60504
Entity Type:	Limited Liability Company: DELAWARE
Name:	CMC MATERIALS, INC.
Street Address:	870 N. Commons Dr.
City:	Aurora
State/Country:	ILLINOIS
Postal Code:	60504
Entity Type:	Corporation: DELAWARE

PROPERTY NUMBERS Total: 64

Property Type	Number	Word Mark
Registration Number:	4372801	ELEMENT
Registration Number:	2363181	EPIC
Registration Number:	2517587	ICUE
Registration Number:	4613239	IDIEL
Registration Number:	2632288	LUSTRA
Registration Number:	5354755	MEDEA
Registration Number:	3702810	NEXPLANAR
Registration Number:	1704025	SEMI-SPERSE
Registration Number:	1917115	SEMI-SPERSE

Property Type	Number	Word Mark
Registration Number:	3103184	SILECT
Registration Number:	3623364	TRANSELE
Registration Number:	3456932	WIN
Registration Number:	3451884	EPOCH
Registration Number:	2499905	ETERPOL
Registration Number:	3737365	ASI
Registration Number:	2827173	MRF
Registration Number:	4303897	QED OPTICS
Registration Number:	2777617	QED TECHNOLOGIES
Registration Number:	4270737	Q-FLEX
Registration Number:	2971771	TURBOFLO
Registration Number:	1851237	CLEANROOM
Registration Number:	1705722	GIGABIT
Registration Number:	3949164	NANO-STRIP
Registration Number:	3306579	NANO-STRIP
Registration Number:	1533823	PARTICU-LO
Registration Number:	2189410	PARTICU-LO LTM
Registration Number:	1870262	TERABIT
Registration Number:	1907795	ULTRA-ETCH
Registration Number:	0821851	BUENO
Registration Number:	0821805	DACONATE
Registration Number:	2994247	HIPR
Registration Number:	2243649	X-PAND
Registration Number:	2142260	SEALWELD
Registration Number:	5514442	FLOW WOLF
Registration Number:	5514443	CHAMELEON SEAL
Registration Number:	5520231	ACTIV-8
Registration Number:	5498636	VALVE CLEANER PLUS
Registration Number:	4053560	VIPER
Registration Number:	5947138	PROBE REFRESH
Registration Number:	5947139	PROBE VERTICAL
Registration Number:	4479239	ETCH CLEAN
Registration Number:	4517513	STAGE CLEAN
Registration Number:	3725048	CCW
Registration Number:	3725049	SCD
Registration Number:	3820328	TCC
Registration Number:	3660513	PROBE POLISH
Registration Number:	3660514	PROBE SCRUB

Property Type	Number	Word Mark
Registration Number:	3660499	PROBE CLEAN
Registration Number:	3251735	PROBE LAP
Registration Number:	2642325	PROBE FORM
Registration Number:	2610970	PROBE POLISH
Registration Number:	2651534	INTERNATIONAL TEST SOLUTIONS
Registration Number:	2599807	PROBE CLEAN
Registration Number:	2599808	PROBE SCRUB
Registration Number:	6010732	SEALVALVE
Registration Number:	5944473	EQUA-LUBE EIGHTY
Registration Number:	5638495	TOTAL-LUBE #911
Registration Number:	5969362	SEALVALVE
Registration Number:	6085978	SEALWELD
Registration Number:	5807265	GRIZZLY SEAL
Registration Number:	5938369	VALVEPRO
Registration Number:	5938368	SUPERGUN
Registration Number:	5633402	UNI-SEAL
Registration Number:	5788180	AUSCILLATER

CORRESPONDENCE DATA

Fax Number: 8009144240

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 800-713-0755

Email: Michael.Violet@wolterskluwer.com, ECarrera@cahill.com

Correspondent Name: CT Corporation

Address Line 1: 4400 Easton Commons Way

Address Line 2: Suite 125

Address Line 4: Columbus, OHIO 43219

NAME OF SUBMITTER:	Elaine Carrera
SIGNATURE:	/Elaine Carrera/
DATE SIGNED:	07/06/2022

Total Attachments: 42

source=CMC - IP Release (Trademarks)#page1.tif
source=CMC - IP Release (Trademarks)#page2.tif
source=CMC - IP Release (Trademarks)#page3.tif
source=CMC - IP Release (Trademarks)#page4.tif
source=CMC - IP Release (Trademarks)#page5.tif
source=CMC - IP Release (Trademarks)#page6.tif
source=CMC - IP Release (Trademarks)#page7.tif
source=CMC - IP Release (Trademarks)#page8.tif
source=CMC - IP Release (Trademarks)#page9.tif

source=CMC - IP Release (Trademarks)#page10.tif
source=CMC - IP Release (Trademarks)#page11.tif
source=CMC - IP Release (Trademarks)#page12.tif
source=CMC - IP Release (Trademarks)#page13.tif
source=CMC - IP Release (Trademarks)#page14.tif
source=CMC - IP Release (Trademarks)#page15.tif
source=CMC - IP Release (Trademarks)#page16.tif
source=CMC - IP Release (Trademarks)#page17.tif
source=CMC - IP Release (Trademarks)#page18.tif
source=CMC - IP Release (Trademarks)#page19.tif
source=CMC - IP Release (Trademarks)#page20.tif
source=CMC - IP Release (Trademarks)#page21.tif
source=CMC - IP Release (Trademarks)#page22.tif
source=CMC - IP Release (Trademarks)#page23.tif
source=CMC - IP Release (Trademarks)#page24.tif
source=CMC - IP Release (Trademarks)#page25.tif
source=CMC - IP Release (Trademarks)#page26.tif
source=CMC - IP Release (Trademarks)#page27.tif
source=CMC - IP Release (Trademarks)#page28.tif
source=CMC - IP Release (Trademarks)#page29.tif
source=CMC - IP Release (Trademarks)#page30.tif
source=CMC - IP Release (Trademarks)#page31.tif
source=CMC - IP Release (Trademarks)#page32.tif
source=CMC - IP Release (Trademarks)#page33.tif
source=CMC - IP Release (Trademarks)#page34.tif
source=CMC - IP Release (Trademarks)#page35.tif
source=CMC - IP Release (Trademarks)#page36.tif
source=CMC - IP Release (Trademarks)#page37.tif
source=CMC - IP Release (Trademarks)#page38.tif
source=CMC - IP Release (Trademarks)#page39.tif
source=CMC - IP Release (Trademarks)#page40.tif
source=CMC - IP Release (Trademarks)#page41.tif
source=CMC - IP Release (Trademarks)#page42.tif

RELEASE OF SECURITY INTEREST IN INTELLECTUAL PROPERTY

This RELEASE OF SECURITY INTEREST IN INTELLECTUAL PROPERTY (this "Release"), dated as of July 6, 2022 (the "Effective Date"), is made by JPMORGAN CHASE BANK, N.A., in its capacity as Collateral Agent (the "Agent"), in favor of the grantor parties identified on the signature pages hereto (each a "Grantor" and, together, the "Grantors").

WHEREAS, pursuant to that certain Collateral Agreement, dated as of November 15, 2018, by and among the Agent, the Grantors and certain other parties thereto (as amended, restated, amended and restated, supplemented or otherwise modified from time to time, the "Collateral Agreement"), the Grantors granted to the Agent, in its capacity as Collateral Agent a security interest in and to certain collateral;

WHEREAS, pursuant to the Collateral Agreement, CABOT MICROELECTRONICS CORPORATION, QED TECHNOLOGIES INTERNATIONAL, INC., FLOWCHEM LLC, KMG ELECTRONIC CHEMICALS, INC., KMG-BERNUTH, INC., MPOWER SPECIALTY CHEMICALS LLC, and SEALWELD (USA), INC. each executed and delivered a Notice of Grant of Security Interest in Trademarks, dated as of November 15, 2018 (the "2018 Trademark Security Agreement"), for recordal with the United States Patent and Trademark Office;

WHEREAS, the 2018 Trademark Security Agreement was recorded with the United States Patent and Trademark Office on November 16, 2018 at Reel/Frame 6483/0177;

WHEREAS, pursuant to the Collateral Agreement, INTERNATIONAL TEST SOLUTIONS, LLC executed and delivered a Notice of Grant of Security Interest in Trademarks, dated as April 30, 2021 (the "ITS Trademark Security Agreement"), for recordal with the United States Patent and Trademark Office;

WHEREAS, the ITS Trademark Security Agreement was recorded with the United States Patent and Trademark Office on April 30, 2021 at Reel/Frame 7276/0107;

WHEREAS, pursuant to the Collateral Agreement, CMC MATERIALS, INC. executed and delivered a Notice of Grant of Security Interest in Trademarks, dated as July 2, 2021 (the "CMC Trademark Security Agreement" and, together with the 2018 Trademark Security Agreement and the ITS Trademark Security Agreement, the "Trademark Security Agreements"), for recordal with the United States Patent and Trademark Office;

WHEREAS, the CMC Trademark Security Agreement was recorded with the United States Patent and Trademark Office on July 2, 2021 at Reel/Frame 7345/0418;

WHEREAS, pursuant to the Collateral Agreement, CABOT MICROELECTRONICS CORPORATION, QED TECHNOLOGIES INTERNATIONAL, INC., FLOWCHEM LLC, KMG ELECTRONIC CHEMICALS, INC., and MPOWER SPECIALTY CHEMICALS LLC each executed and delivered a Notice of Grant of Security Interest in Patents, dated as of November 15, 2018 (the "2018 Patent Security Agreement"), for recordal with the United States Patent and Trademark Office;

WHEREAS, the 2018 Patent Security Agreement was recorded with the United States Patent and Trademark Office on November 16, 2018 at Reel/Frame 047588/0263;

WHEREAS, pursuant to the Collateral Agreement, INTERNATIONAL TEST SOLUTIONS, LLC executed and delivered a Notice of Grant of Security Interest in Patents, dated as April 30, 2021 (the "ITS Patent Security Agreement"), for recordal with the United States Patent and Trademark Office;

WHEREAS, the ITS Patent Security Agreement was recorded with the United States Patent and Trademark Office on April 30, 2021 at Reel/Frame 056104/0979;

WHEREAS, pursuant to the Collateral Agreement, CMC MATERIALS, INC. executed and delivered a Notice of Grant of Security Interest in Patents, dated as July 2, 2021 (the "CMC Patent Security Agreement" and, together with the 2018 Patent Security Agreement and the ITS Patent Security Agreement, the "Patent Security Agreements"), for recordal with the United States Patent and Trademark Office;

WHEREAS, the CMC Patent Security Agreement was recorded with the United States Patent and Trademark Office on July 2, 2021 at Reel/Frame 056752/0645;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the Agent hereby agrees as follows:

1. Defined Terms. All capitalized terms used, but not otherwise defined herein, shall have the respective meanings ascribed in or otherwise referenced in the Collateral Agreement, the Trademark Security Agreements or the Patent Security Agreements, as applicable.

2. Release. The Agent, without representation or warranty of any kind, hereby releases, fully discharges, terminates and cancels all of its continuing security interest in and to the IP Collateral, including the patents and patent applications set forth on Schedule I attached hereto and the trademark registrations and applications set forth on Schedule II attached hereto, in each case arising under the Collateral Agreement, the Trademark Security Agreements and the Patent Security Agreements, as applicable. If and to the extent that the Agent has acquired any right, title or interest in and to the IP Collateral under the Collateral Agreement, Trademark Security Agreements or the Patent Security Agreements, the Agent, without representation or warranty of any kind, hereby re-transfers, re-conveys and re-assigns such right, title or interest to the applicable Grantors.

3. Termination. The Agent, without representation or warranty of any kind, terminates and cancels the Trademark Security Agreements and the Patent Security Agreements.

4. Further Assurances. The Agent agrees to take all further actions, and provide to the Grantors and their successors, assigns or other legal representatives, all such cooperation and assistance (including, without limitation, the execution and delivery of any and all documents or other instruments), reasonably requested by the Grantors, at the Grantors' sole cost and expense, to more fully and effectively effectuate the purposes of this Release.

5. Governing Law. This Release shall be governed exclusively under the laws of the State of New York, without regard to conflicts of law or choice of law principles.

6. Counterparts. This Release may be executed in any number of counterparts, each of which shall be an original, and all of which, when taken together, shall constitute one agreement. The words "execution," "signed," "signature," "delivery," and words of like import in or relating to this Release and/or any document to be signed in connection with this Release and the transactions contemplated hereby shall be deemed to include Electronic Signatures (as defined below), deliveries or the keeping of records in electronic form, each of which shall be of the same legal effect, validity or enforceability as a manually executed signature, physical delivery thereof or the use of a paper-based recordkeeping system, as the case

TRADEMARK
REEL: 007771 FRAME: 0736

may be. "Electronic Signatures" means any electronic symbol or process attached to, or associated with, any contract or other record and adopted by a person with the intent to sign, authenticate or accept such contract or record.

[Signature Pages Follow]

TRADEMARK
REEL: 007771 FRAME: 0737

IN WITNESS WHEREOF, the Agent has caused this Release to be executed by its duly authorized representative as of the Effective Date:

JPMORGAN CHASE BANK, N.A. acting in its capacity as Collateral Agent

By: ______________________________
Name: Eleftherios Karsos
Title: Authorized Officer

GRANTORS:
CABOT MICROELECTRONICS CORPORATION
QED TECHNOLOGIES INTERNATIONAL, INC.
FLOWCHEM LLC
KMG ELECTRONIC CHEMICALS, INC.
KMG-BERNUTH, INC.
MPOWER SPECIALTY CHEMICALS LLC
SEALWELD (USA), INC.
INTERNATIONAL TEST SOLUTIONS, LLC
CMC MATERIALS, INC.

<u>SCHEDULE I</u>

Release of Notice of Grant of Security Interest in Patents recorded November 16, 2018 at Reel/Frame 047588/0263

<u>**Patents**</u>

UNITED STATES PATENTS:

U.S. Patent Registrations:

	OWNER	REGISTRATION NUMBER	DESCRIPTION
1.	CABOT MICROELECTRONICS CORPORATION	10,029,345	METHODS AND COMPOSITIONS FOR PROCESSING DIELECTRIC SUBSTRATE
2.	CABOT MICROELECTRONICS CORPORATION	10,066,126	TUNGSTEN PROCESSING SLURRY WITH CATALYST
3.	CABOT MICROELECTRONICS CORPORATION	6,293,848	COMPOSITION AND METHOD FOR PLANARIZING SURFACES
4.	CABOT MICROELECTRONICS CORPORATION	10,100,272	CLEANING COMPOSITION FOLLOWING CMP AND METHODS RELATED THERETO
5.	CABOT MICROELECTRONICS CORPORATION	6,316,365	CHEMICAL-MECHANICAL POLISHING METHOD
6.	CABOT MICROELECTRONICS CORPORATION	6,319,096	COMPOSITION AND METHOD FOR PLANARIZING SURFACES
7.	CABOT MICROELECTRONICS CORPORATION	6,347,978	COMPOSITION AND METHOD FOR POLISHING RIGID DISKS
8.	CABOT MICROELECTRONICS CORPORATION	6,348,076	SLURRY FOR MECHANICAL POLISHING (CMP) OF METALS AND USE THEREOF
9.	CABOT MICROELECTRONICS CORPORATION	6,350,393	USE OF CSOH IN A DIELECTRIC CMP SLURRY
10.	CABOT MICROELECTRONICS CORPORATION	6,375,693	CHEMICAL-MECHANICAL PLANARIZATION OF BARRIERS OR LINERS FOR COPPER METALLURGY
11.	CABOT MICROELECTRONICS CORPORATION	6,383,065	CATALYTIC REACTIVE PAD FOR METAL CMP
12.	CABOT MICROELECTRONICS CORPORATION	6,395,693	CLEANING SOLUTION FOR SEMICONDUCTOR SURFACES FOLLOWING CHEMICAL-MECHANICAL POLISHING
13.	CABOT MICROELECTRONICS CORPORATION	6,409,781	POLISHING SLURRIES FOR COPPER AND ASSOCIATED MATERIALS

	OWNER	REGISTRATION NUMBER	DESCRIPTION
14.	CABOT MICROELECTRONICS CORPORATION	6,461,227	METHOD OF POLISHING A MEMORY OR RIGID DISK WITH AN AMMONIA AND/OR HALIDE CONTAINING COMPOSITION
15.	CABOT MICROELECTRONICS CORPORATION	6,468,137	METHOD FOR POLISHING A MEMORY OR RIGID DISK WITH AN OXIDIZED HALIDE-CONTAINING POLISHING SYSTEM
16.	CABOT MICROELECTRONICS CORPORATION	6,471,884	METHOD FOR POLISHING A MEMORY OR RIGID DISK WITH AN AMINO ACID-CONTAINING COMPOSITION
17.	CABOT MICROELECTRONICS CORPORATION	6,527,622	CMP METHOD FOR NOBLE METALS
18.	CABOT MICROELECTRONICS CORPORATION	6,527,817	COMPOSITION AND METHOD FOR PLANARIZING SURFACES
19.	CABOT MICROELECTRONICS CORPORATION	6,527,819	POLISHING SLURRIES FOR COPPER AND ASSOCIATED MATERIALS
20.	CABOT MICROELECTRONICS CORPORATION	6,541,434	CLEANING SOLUTION FOR SEMICONDUCTOR SURFACES FOLLOWING CHEMICAL-MECHANICAL POLISHING
21.	CABOT MICROELECTRONICS CORPORATION	6,569,350 (Expired)	CHEMICAL MECHANICAL POLISHING SLURRY USEFUL FOR COPPER SUBSTRATES
22.	CABOT MICROELECTRONICS CORPORATION	6,582,623	CMP COMPOSITION CONTAINING SILANE MODIFIED ABRASIVE PARTICLES
23.	CABOT MICROELECTRONICS CORPORATION	6,589,100	RARE EARTH SALT/OXIDIZER-BASED CMP METHOD
24.	CABOT MICROELECTRONICS CORPORATION	6,592,776	POLISHING COMPOSITION FOR METAL CMP
25.	CABOT MICROELECTRONICS CORPORATION	6,623,331	POLISHING DISK WITH END-POINT DETECTION PORT
26.	CABOT MICROELECTRONICS CORPORATION	6,632,377	CHEMICAL-MECHANICAL PLANARIZATION OF METALLURGY
27.	CABOT MICROELECTRONICS CORPORATION	6,641,632	POLISHING COMPOSITIONS AND USE THEREOF
28.	CABOT MICROELECTRONICS CORPORATION	6,646,348	SILANE CONTAINING POLISHING COMPOSITION FOR CMP
29.	CABOT MICROELECTRONICS CORPORATION	6,682,575	METHANOL-CONTAINING SILICA-BASED CMP COMPOSITIONS

	OWNER	REGISTRATION NUMBER	DESCRIPTION
30.	CABOT MICROELECTRONICS CORPORATION	6,705,926	BORON-CONTAINING POLISHING SYSTEM AND METHOD
31.	CABOT MICROELECTRONICS CORPORATION	6,767,476 (Expired)	POLISHING COMPOSITION FOR METAL CMP
32.	CABOT MICROELECTRONICS CORPORATION	6,776,810	ANIONIC ABRASIVE PARTICLES TREATED WITH POSITIVELY CHARGED POLYELECTROLYTES FOR CMP
33.	CABOT MICROELECTRONICS CORPORATION	6,811,474	POLISHING COMPOSITION CONTAINING CONDUCTING POLYMER
34.	CABOT MICROELECTRONICS CORPORATION	6,812,193	SLURRY FOR MECHANICAL POLISHING (CMP) OF METALS AND USE THEREOF
35.	CABOT MICROELECTRONICS CORPORATION	6,821,897	METHOD FOR COPPER CMP USING POLYMERIC COMPLEXING AGENTS
36.	CABOT MICROELECTRONICS CORPORATION	6,830,503	CATALYST/OXIDIZER-BASED CMP SYSTEM FOR ORGANIC POLYMER FILMS
37.	CABOT MICROELECTRONICS CORPORATION	6,840,843	METHOD FOR MANUFACTURING A POLISHING PAD HAVING A COMPRESSED TRANSLUCENT REGION
38.	CABOT MICROELECTRONICS CORPORATION	6,840,971	CHEMICAL MECHANICAL POLISHING SYSTEMS AND METHODS FOR THEIR USE
39.	CABOT MICROELECTRONICS CORPORATION	6,852,632	METHOD OF POLISHING A MULTI-LAYER SUBSTRATE
40.	CABOT MICROELECTRONICS CORPORATION	6,855,266	POLISHING SYSTEM WITH STOPPING COMPOUND AND METHOD OF ITS USE
41.	CABOT MICROELECTRONICS CORPORATION	6,867,140	METHOD OF POLISHING A MULTI-LAYER SUBSTRATE
42.	CABOT MICROELECTRONICS CORPORATION	6,872,328	METHOD OF POLISHING OR PLANARIZING A SUBSTRATE
43.	CABOT MICROELECTRONICS CORPORATION	6,884,156	MULTI-LAYER POLISHING PAD MATERIAL FOR CMP
44.	CABOT MICROELECTRONICS CORPORATION	6,896,591	MIXED-ABRASIVE POLISHING COMPOSITION AND METHOD FOR USING THE SAME
45.	CABOT MICROELECTRONICS CORPORATION	6,896,593	MICROPOROUS POLISHING PADS
46.	CABOT MICROELECTRONICS CORPORATION	6,899,598	MICROPOROUS POLISHING PADS
47.	CABOT MICROELECTRONICS CORPORATION	6,913,517	MICROPOROUS POLISHING PADS

	OWNER	REGISTRATION NUMBER	DESCRIPTION
48.	CABOT MICROELECTRONICS CORPORATION	6,935,931	MICROPOROUS POLISHING PADS
49.	CABOT MICROELECTRONICS CORPORATION	6,936,542	POLISHING SLURRIES FOR COPPER AND ASSOCIATED MATERIALS
50.	CABOT MICROELECTRONICS CORPORATION	6,936,543	USE OF NON-IONIC SURFACTANTS TO REDUCE TA AND OXIDE REMOVAL RATE
51.	CABOT MICROELECTRONICS CORPORATION	6,960,120	CMP PAD WITH COMPOSITE TRANSPARENT WINDOW
52.	CABOT MICROELECTRONICS CORPORATION	6,974,777	CMP COMPOSITIONS FOR LOW-K DIELECTRIC MATERIALS
53.	CABOT MICROELECTRONICS CORPORATION	6,997,777	ULTRASONIC WELDING METHOD FOR THE MANUFACTURE OF A POLISHING PAD COMPRISING AN OPTICALLY TRANSMISSIVE REGION
54.	CABOT MICROELECTRONICS CORPORATION	6,998,166	POLISHING PAD WITH ORIENTED PORE STRUCTURE
55.	CABOT MICROELECTRONICS CORPORATION	7,004,819	CMP SYSTEMS AND METHODS UTILIZING AMINE-CONTAINING POLYMERS
56.	CABOT MICROELECTRONICS CORPORATION	7,044,836	COATED METAL OXIDE PARTICLES FOR CMP
57.	CABOT MICROELECTRONICS CORPORATION	7,059,936	LOW SURFACE ENERGY CMP PAD
58.	CABOT MICROELECTRONICS CORPORATION	7,097,541	CMP METHOD FOR NOBLE METALS
59.	CABOT MICROELECTRONICS CORPORATION	7,160,807	CMP OF NOBLE METALS
60.	CABOT MICROELECTRONICS CORPORATION	7,161,247	POLISHING COMPOSITION FOR NOBLE METALS
61.	CABOT MICROELECTRONICS CORPORATION	7,195,539	POLISHING PAD WITH RECESSED WINDOW
62.	CABOT MICROELECTRONICS CORPORATION	7,195,544	CMP POROUS PAD WITH COMPONENT-FILLED PORES
63.	CABOT MICROELECTRONICS CORPORATION	7,198,549	CONTINUOUS CONTOUR POLISHING OF A MULTI-MATERIAL SURFACE
64.	CABOT MICROELECTRONICS CORPORATION	7,204,742	POLISHING PAD COMPRISING HYDROPHOBIC REGION AND ENDPOINT DETECTION PORT

	OWNER	REGISTRATION NUMBER	DESCRIPTION
65.	CABOT MICROELECTRONICS CORPORATION	7,238,618	SYSTEM FOR THE PREFERENTIAL REMOVAL OF SILICON OXIDE
66.	CABOT MICROELECTRONICS CORPORATION	7,247,567	METHOD OF POLISHING A TUNGSTEN-CONTAINING SUBSTRATE
67.	CABOT MICROELECTRONICS CORPORATION	7,255,810	POLISHING SYSTEM COMPRISING A HIGHLY BRANCHED POLYMER
68.	CABOT MICROELECTRONICS CORPORATION	7,265,055	CMP OF COPPER/RUTHENIUM SUBSTRATES
69.	CABOT MICROELECTRONICS CORPORATION	7,267,607	TRANSPARENT MICROPOROUS MATERIALS FOR CMP
70.	CABOT MICROELECTRONICS CORPORATION	7,288,021	CHEMICAL-MECHANICAL POLISHING OF METALS IN AN OXIDIZED FORM
71.	CABOT MICROELECTRONICS CORPORATION	7,294,576	TUNABLE SELECTIVITY SLURRIES IN CMP APPLICATIONS
72.	CABOT MICROELECTRONICS CORPORATION	7,306,637	ANIONIC ABRASIVE PARTICLES TREATED WITH POSITIVELY CHARGED POLYELECTROLYTES FOR CMP
73.	CABOT MICROELECTRONICS CORPORATION	7,311,856	POLYMERIC INHIBITORS FOR ENHANCED PLANARIZATION
74.	CABOT MICROELECTRONICS CORPORATION	7,311,862	METHOD FOR MANUFACTURING MICROPOROUS CMP MATERIALS HAVING CONTROLLED PORE SIZE
75.	CABOT MICROELECTRONICS CORPORATION	7,316,603	COMPOSITIONS AND METHODS FOR TANTALUM CMP
76.	CABOT MICROELECTRONICS CORPORATION	7,354,530	CHEMICAL MECHANICAL POLISHING SYSTEMS AND METHODS FOR THEIR USE
77.	CABOT MICROELECTRONICS CORPORATION	7,368,066	GOLD CMP COMPOSITION AND METHOD
78.	CABOT MICROELECTRONICS CORPORATION	7,377,840	METHODS FOR PRODUCING IN-SITU GROOVES IN CHEMICAL MECHANICAL PLANARIZATION (CMP) PADS, AND NOVEL CMP PAD DESIGNS
79.	CABOT MICROELECTRONICS CORPORATION	7,381,648	CHEMICAL MECHANICAL POLISHING SLURRY USEFUL FOR COPPER SUBSTRATES
80.	CABOT MICROELECTRONICS CORPORATION	7,425,172	CUSTOMIZED POLISH PADS FOR CHEMICAL MECHANICAL PLANARIZATION
81.	CABOT MICROELECTRONICS CORPORATION	7,427,567	POLISHING SLURRIES FOR COPPER AND ASSOCIATED MATERIALS

	OWNER	REGISTRATION NUMBER	DESCRIPTION
82.	CABOT MICROELECTRONICS CORPORATION	7,435,161	MULTI-LAYER POLISHING PAD MATERIAL FOR CMP
83.	CABOT MICROELECTRONICS CORPORATION	7,435,165	TRANSPARENT MICROPOROUS MATERIALS FOR CMP
84.	CABOT MICROELECTRONICS CORPORATION	7,442,645	METHOD OF POLISHING A SILICON-CONTAINING DIELECTRIC
85.	CABOT MICROELECTRONICS CORPORATION	7,447,298	DECONTAMINATION AND STERILIZATION SYSTEM USING LARGE AREA X-RAY SOURCE
86.	CABOT MICROELECTRONICS CORPORATION	7,456,107	COMPOSITIONS AND METHODS FOR CMP OF LOW-K DIELECTRIC MATERIALS
87.	CABOT MICROELECTRONICS CORPORATION	7,485,241	CHEMICAL MECHANICAL POLISHING COMPOSITION AND METHOD FOR USING THE SAME
88.	CABOT MICROELECTRONICS CORPORATION	7,501,346	GALLIUM AND CHROMIUM IONS FOR OXIDE RATE ENHANCEMENT
89.	CABOT MICROELECTRONICS CORPORATION	7,504,044	POLISHING COMPOSITION AND METHOD FOR HIGH SILICON NITRIDE TO SILICON OXIDE REMOVAL RATE RATIOS
90.	CABOT MICROELECTRONICS CORPORATION	7,524,347	CMP COMPOSITION COMPRISING SURFACTANT
91.	CABOT MICROELECTRONICS CORPORATION	7,531,105	POLISHING COMPOSITION AND METHOD FOR HIGH SILICON NITRIDE TO SILICON OXIDE REMOVAL RATE RATIOS
92.	CABOT MICROELECTRONICS CORPORATION	7,563,383	CMP COMPOSITION WITH A POLYMER ADDITIVE FOR POLISHING NOBLE METALS
93.	CABOT MICROELECTRONICS CORPORATION	7,582,127	METHOD OF POLISHING A TUNGSTEN-CONTAINING SUBSTRATE
94.	CABOT MICROELECTRONICS CORPORATION	7,585,340	POLISHING COMPOSITION CONTAINING POLYETHER AMINE
95.	CABOT MICROELECTRONICS CORPORATION	7,677,956	COMPOSITIONS AND METHODS FOR DIELECTRIC CMP
96.	CABOT MICROELECTRONICS CORPORATION	7,678,700	SILICON CARBIDE POLISHING METHOD UTILIZING WATER-SOLUBLE OXIDIZERS
97.	CABOT MICROELECTRONICS CORPORATION	7,704,122	CUSTOMIZED POLISH PADS FOR CHEMICAL MECHANICAL PLANARIZATION
98.	CABOT MICROELECTRONICS CORPORATION	7,704,125	CUSTOMIZED POLISH PADS FOR CMP AND METHODS OF FABRICATION AND USE THEREOF

	OWNER	REGISTRATION NUMBER	DESCRIPTION
99.	CABOT MICROELECTRONICS CORPORATION	7,754,098	CHEMICAL MECHANICAL POLISHING COMPOSITION AND METHOD FOR USING THE SAME
100.	CABOT MICROELECTRONICS CORPORATION	7,776,230	CMP SYSTEM UTILIZING HALOGEN ADDUCT
101.	CABOT MICROELECTRONICS CORPORATION	7,803,203	COMPOSITIONS AND METHODS FOR CMP OF SEMICONDUCTOR MATERIALS
102.	CABOT MICROELECTRONICS CORPORATION	7,803,711	LOW PH BARRIER SLURRY BASED ON TITANIUM DIOXIDE
103.	CABOT MICROELECTRONICS CORPORATION	7,820,067	HALIDE ANIONS FOR METAL REMOVAL RATE CONTROL
104.	CABOT MICROELECTRONICS CORPORATION	7,837,888	COMPOSITION AND METHOD FOR DAMASCENE CMP
105.	CABOT MICROELECTRONICS CORPORATION	7,846,842	POLISHING COMPOSITION AND METHOD FOR HIGH SILICON NITRIDE TO SILICON OXIDE REMOVAL RATE RATIOS
106.	CABOT MICROELECTRONICS CORPORATION	7,897,061	COMPOSITIONS AND METHODS FOR CMP OF PHASE CHANGE ALLOYS COMPOSITIONS AND METHODS FOR CMP OF PHASE CHANGE ALLOYS
107.	CABOT MICROELECTRONICS CORPORATION	7,922,926	COMPOSITION AND METHOD FOR POLISHING NICKEL-PHOSPHOROUS-COATED ALUMINUM HARD DISKS
108.	CABOT MICROELECTRONICS CORPORATION	7,955,519	COMPOSITION AND METHOD FOR PLANARIZING SURFACES
109.	CABOT MICROELECTRONICS CORPORATION	7,955,520	COPPER-PASSIVATING CMP COMPOSITIONS AND METHODS
110.	CABOT MICROELECTRONICS CORPORATION	7,994,057	POLISHING COMPOSITION AND METHOD UTILIZING ABRASIVE PARTICLES TREATED WITH AN AMINOSILANE
111.	CABOT MICROELECTRONICS CORPORATION	7,998,228	TANTALUM CMP COMPOSITIONS AND METHODS
112.	CABOT MICROELECTRONICS CORPORATION	7,998,866	SILICON CARBIDE POLISHING METHOD UTILIZING WATER-SOLUBLE OXIDIZERS
113.	CABOT MICROELECTRONICS CORPORATION	8,008,202	RUTHENIUM CMP COMPOSITIONS AND METHODS
114.	CABOT MICROELECTRONICS CORPORATION	8,017,524	STABLE, HIGH RATE SILICON SLURRY

	OWNER	REGISTRATION NUMBER	DESCRIPTION
115.	CABOT MICROELECTRONICS CORPORATION	8,038,752	METAL ION-CONTAINING CMP COMPOSITION AND METHOD FOR USING THE SAME
116.	CABOT MICROELECTRONICS CORPORATION	8,057,561	POLYOXOMETALATE COMPOSITIONS AND METHODS
117.	CABOT MICROELECTRONICS CORPORATION	8,062,096	USE OF CMP FOR ALUMINUM MIRROR AND SOLAR CELL FABRICATION
118.	CABOT MICROELECTRONICS CORPORATION	8,075,372	POLISHING PAD WITH MICROPOROUS REGIONS
119.	CABOT MICROELECTRONICS CORPORATION	8,101,093	CHEMICAL-MECHANICAL POLISHING COMPOSITION AND METHOD FOR USING THE SAME
120.	CABOT MICROELECTRONICS CORPORATION	8,138,091	POLISHING COMPOSITION AND METHOD FOR HIGH SILICON NITRIDE TO SILICON OXIDE REMOVAL RATE RATIOS
121.	CABOT MICROELECTRONICS CORPORATION	8,157,876	SLURRY COMPOSITION CONTAINING NON-IONIC POLYMER AND METHOD FOR USE
122.	CABOT MICROELECTRONICS CORPORATION	8,162,723	METHOD OF POLISHING A TUNGSTEN CARBIDE SURFACE
123.	CABOT MICROELECTRONICS CORPORATION	8,226,841	POLISHING COMPOSITION FOR NICKEL-PHOSPHOROUS MEMORY DISKS
124.	CABOT MICROELECTRONICS CORPORATION	8,247,326	METHOD OF POLISHING NICKEL-PHOSPHOROUS
125.	CABOT MICROELECTRONICS CORPORATION	8,247,327	METHODS AND COMPOSITIONS FOR POLISHING SILICON-CONTAINING SUBSTRATES
126.	CABOT MICROELECTRONICS CORPORATION	8,247,328	POLISHING SILICON CARBIDE
127.	CABOT MICROELECTRONICS CORPORATION	8,251,777	POLISHING SLURRY FOR ALUMINUM AND ALUMINUM ALLOYS
128.	CABOT MICROELECTRONICS CORPORATION	8,252,687	BARRIER SLURRY FOR LOW-K DIELECTRICS
129.	CABOT MICROELECTRONICS CORPORATION	8,273,142	SILICON POLISHING COMPOSITIONS WITH HIGH RATE AND LOW DEFECTIVITY
130.	CABOT MICROELECTRONICS CORPORATION	8,287,793	METHODS FOR PRODUCING IN-SITU GROOVES IN CHEMICAL MECHANICAL PLANARIZATION (CMP) PADS, AND NOVEL CMP PAD DESIGNS
131.	CABOT MICROELECTRONICS CORPORATION	8,380,339	CUSTOMIZED POLISH PADS FOR CHEMICAL MECHANICAL PLANARIZATION

	OWNER	REGISTRATION NUMBER	DESCRIPTION
132.	CABOT MICROELECTRONICS CORPORATION	8,383,003	POLISHING SYSTEMS
133.	CABOT MICROELECTRONICS CORPORATION	8,425,797	COMPOSITIONS FOR POLISHING ALUMINUM/COPPER AND TITANIUM IN DAMASCENE STRUCTURES
134.	CABOT MICROELECTRONICS CORPORATION	8,435,421	METAL-PASSIVATING CMP COMPOSITIONS AND METHODS
135.	CABOT MICROELECTRONICS CORPORATION	8,439,994	METHOD OF FABRICATING A POLISHING PAD WITH AN END-POINT DETECTION REGION FOR EDDY CURRENT END-POINT DETECTION
136.	CABOT MICROELECTRONICS CORPORATION	8,486,169	METHOD OF POLISHING A SILICON-CONTAINING DIELECTRIC
137.	CABOT MICROELECTRONICS CORPORATION	8,497,209	OXIDATION-STABILIZED CMP COMPOSITIONS AND METHODS
138.	CABOT MICROELECTRONICS CORPORATION	8,518,135	POLISHING COMPOSITION CONTAINING HYBRID ABRASIVE FOR NICKEL-PHOSPHOROUS COATED MEMORY DISKS
139.	CABOT MICROELECTRONICS CORPORATION	8,529,680	COMPOSITIONS FOR CMP OF SEMICONDUCTOR MATERIALS
140.	CABOT MICROELECTRONICS CORPORATION	8,541,310	CMP COMPOSITIONS CONTAINING A SOLUBLE PEROXOMETALATE COMPLEX AND METHODS OF USE THEREOF
141.	CABOT MICROELECTRONICS CORPORATION	8,551,202	IODATE-CONTAINING CHEMICAL-MECHANICAL POLISHING COMPOSITIONS AND METHODS
142.	CABOT MICROELECTRONICS CORPORATION	8,557,137	POLISHING COMPOSITION FOR NICKEL-PHOSPHOROUS MEMORY DISKS
143.	CABOT MICROELECTRONICS CORPORATION	8,591,763	HALIDE ANIONS FOR METAL REMOVAL RATE CONTROL
144.	CABOT MICROELECTRONICS CORPORATION	8,597,538	COMPOSITION FOR IMPROVING DRYNESS DURING WIRE SAWING
145.	CABOT MICROELECTRONICS CORPORATION	8,597,540	COMPOSITIONS FOR POLISHING SILICON-CONTAINING SUBSTRATES
146.	CABOT MICROELECTRONICS CORPORATION	8,623,766	COMPOSITION AND METHOD FOR POLISHING ALUMINUM SEMICONDUCTOR SUBSTRATES
147.	CABOT MICROELECTRONICS CORPORATION	8,623,767	METHOD FOR POLISHING ALUMINUM/COPPER AND TITANIUM IN DAMASCENE STRUCTURES

	OWNER	REGISTRATION NUMBER	DESCRIPTION
148.	CABOT MICROELECTRONICS CORPORATION	8,628,384	POLISHING PAD FOR EDDY CURRENT END-POINT DETECTION
149.	CABOT MICROELECTRONICS CORPORATION	8,637,404	METAL CATIONS FOR INITIATING POLISHING
150.	CABOT MICROELECTRONICS CORPORATION	8,657,653	HOMOGENEOUS POLISHING PAD FOR EDDY CURRENT END-POINT DETECTION
151.	CABOT MICROELECTRONICS CORPORATION	8,691,695	CMP COMPOSITIONS AND METHODS FOR SUPPRESSING POLYSILICON REMOVAL RATES
152.	CABOT MICROELECTRONICS CORPORATION	8,697,576	COMPOSITION AND METHOD FOR POLISHING POLYSILICON
153.	CABOT MICROELECTRONICS CORPORATION	8,702,479	POLISHING PAD WITH MULTI-MODAL DISTRIBUTION OF PORE DIAMETERS
154.	CABOT MICROELECTRONICS CORPORATION	8,715,035	CUSTOMIZED POLISHING PADS FOR CMP AND METHODS OF FABRICATION AND USE THEREOF
155.	CABOT MICROELECTRONICS CORPORATION	8,741,009	POLISHING COMPOSITION CONTAINING POLYETHER AMINE
156.	CABOT MICROELECTRONICS CORPORATION	8,759,216	COMPOSITIONS AND METHODS FOR POLISHING SILICON NITRIDE MATERIALS
157.	CABOT MICROELECTRONICS CORPORATION	8,778,211	GST CMP SLURRIES
158.	CABOT MICROELECTRONICS CORPORATION	8,778,212	CMP COMPOSITION CONTAINING ZIRCONIA PARTICLES AND METHOD OF USE
159.	CABOT MICROELECTRONICS CORPORATION	8,808,573	COMPOSITIONS AND METHODS FOR SELECTIVE POLISHING OF SILICON NITRIDE MATERIALS
160.	CABOT MICROELECTRONICS CORPORATION	8,815,110	COMPOSITION AND METHOD FOR POLISHING BULK SILICON
161.	CABOT MICROELECTRONICS CORPORATION	8,821,215	POLYPYRROLIDONE POLISHING COMPOSITION AND METHOD
162.	CABOT MICROELECTRONICS CORPORATION	8,864,859	CUSTOMIZED POLISH PADS FOR CMP AND METHODS OF FABRICATION AND USE THEREOF
163.	CABOT MICROELECTRONICS CORPORATION	8,883,034	COMPOSITION AND METHOD FOR POLISHING BULK SILICON
164.	CABOT MICROELECTRONICS CORPORATION	8,906,252	CMP COMPOSITIONS SELECTIVE FOR OXIDE AND NITRIDE WITH HIGH REMOVAL RATE AND LOW DEFECTIVITY

	OWNER	REGISTRATION NUMBER	DESCRIPTION
165.	CABOT MICROELECTRONICS CORPORATION	8,916,061	CMP COMPOSITIONS SELECTIVE FOR OXIDE AND NITRIDE WITH HIGH REMOVAL RATE AND LOW DEFECTIVITY
166.	CABOT MICROELECTRONICS CORPORATION	8,920,219	POLISHING PAD WITH ALIGNMENT APERTURE
167.	CABOT MICROELECTRONICS CORPORATION	8,920,667	CHEMICAL-MECHANICAL POLISHING COMPOSITION CONTAINING ZIRCONIA AND METAL OXIDIZER
168.	CABOT MICROELECTRONICS CORPORATION	8,932,116	METHODS FOR PRODUCING IN-SITU GROOVES IN CHEMICAL MECHANICAL PLANARIZATION (CMP) PADS, AND NOVEL CMP PAD DESIGNS
169.	CABOT MICROELECTRONICS CORPORATION	8,960,177	WIRESAW CUTTING METHOD
170.	CABOT MICROELECTRONICS CORPORATION	8,961,807	CMP COMPOSITIONS WITH LOW SOLIDS CONTENT AND METHODS RELATED THERETO
171.	CABOT MICROELECTRONICS CORPORATION	8,968,058	POLISHING PAD WITH ALIGNMENT FEATURE
172.	CABOT MICROELECTRONICS CORPORATION	9,017,140	CMP PAD WITH LOCAL AREA TRANSPARENCY
173.	CABOT MICROELECTRONICS CORPORATION	9,028,302	POLISHING PAD FOR EDDY CURRENT END-POINT DETECTION
174.	CABOT MICROELECTRONICS CORPORATION	9,028,572	POLISHING COMPOSITION AND METHOD UTILIZING ABRASIVE PARTICLES TREATED WITH AN AMINOSILANE
175.	CABOT MICROELECTRONICS CORPORATION	9,039,914	POLISHING COMPOSITION FOR NICKEL-PHOSPHOROUS-COATED MEMORY DISKS
176.	CABOT MICROELECTRONICS CORPORATION	9,067,297	POLISHING PAD WITH FOUNDATION LAYER AND POLISHING SURFACE LAYER
177.	CABOT MICROELECTRONICS CORPORATION	9,067,298	POLISHING PAD WITH GROOVED FOUNDATION LAYER AND POLISHING SURFACE LAYER
178.	CABOT MICROELECTRONICS CORPORATION	9,074,118 B2	CMP METHOD FOR METAL-CONTAINING SUBSTRATES
179.	CABOT MICROELECTRONICS CORPORATION	9,127,187	MIXED ABRASIVE TUNGSTEN CMP COMPOSITION
180.	CABOT MICROELECTRONICS CORPORATION	9,129,907	ONIUM-CONTAINING CMP COMPOSITIONS AND METHODS OF USE THEREOF

	OWNER	REGISTRATION NUMBER	DESCRIPTION
181.	CABOT MICROELECTRONICS CORPORATION	9,156,124	SOFT POLISHING PAD FOR POLISHING A SEMICONDUCTOR SUBSTRATE
182.	CABOT MICROELECTRONICS CORPORATION	9,156,125	POLISHING PAD WITH LIGHT-STABLE LIGHT-TRANSMITTING REGION
183.	CABOT MICROELECTRONICS CORPORATION	9,165,489	CMP COMPOSITIONS SELECTIVE FOR OXIDE OVER POLYSILICON AND NITRIDE WITH HIGH REMOVAL RATE AND LOW DEFECTIVITY
184.	CABOT MICROELECTRONICS CORPORATION	9,180,570	GROOVED CMP PAD
185.	CABOT MICROELECTRONICS CORPORATION	9,211,628	POLISHING PAD WITH CONCENTRIC OR APPROXIMATELY CONCENTRIC POLYGON GROOVE PATTERN
186.	CABOT MICROELECTRONICS CORPORATION	9,238,294	POLISHING PAD HAVING POROGENS WITH LIQUID FILLER
187.	CABOT MICROELECTRONICS CORPORATION	9,238,753	CMP COMPOSITIONS SELECTIVE FOR OXIDE AND NITRIDE WITH HIGH REMOVAL RATE AND LOW DEFECTIVITY
188.	CABOT MICROELECTRONICS CORPORATION	9,238,754	COMPOSITION FOR TUNGSTEN CMP
189.	CABOT MICROELECTRONICS CORPORATION	9,249,273	POLISHING PAD WITH ALIGNMENT FEATURE
190.	CABOT MICROELECTRONICS CORPORATION	9,272,388	POLISHING SYSTEMS
191.	CABOT MICROELECTRONICS CORPORATION	9,278,424	CUSTOMIZED POLISHING PADS FOR CMP AND METHODS OF FABRICATION AND USE THEREOF
192.	CABOT MICROELECTRONICS CORPORATION	9,279,067	WET-PROCESS CERIA COMPOSITIONS FOR SELECTIVELY POLISHING SUBSTRATES, AND METHODS RELATED THERETO
193.	CABOT MICROELECTRONICS CORPORATION	9,281,210	WET-PROCESS CERIA COMPOSITIONS FOR POLISHING SUBSTRATES, AND METHODS RELATED THERETO
194.	CABOT MICROELECTRONICS CORPORATION	9,296,085	POLISHING PAD WITH HOMOGENEOUS BODY HAVING DISCRETE PROTRUSIONS THEREON
195.	CABOT MICROELECTRONICS CORPORATION	9,303,187	COMPOSITIONS AND METHODS FOR CMP OF SILICON OXIDE, SILICON NITRIDE, AND POLYSILICON MATERIALS

	OWNER	REGISTRATION NUMBER	DESCRIPTION
196.	CABOT MICROELECTRONICS CORPORATION	9,303,188	COMPOSITION FOR TUNGSTEN CMP
197.	CABOT MICROELECTRONICS CORPORATION	9,303,189	COMPOSITION FOR TUNGSTEN CMP
198.	CABOT MICROELECTRONICS CORPORATION	9,303,190	MIXED ABRASIVE TUNGSTEN CMP COMPOSITION
199.	CABOT MICROELECTRONICS CORPORATION	9,309,442	COMPOSITION FOR TUNGSTEN BUFFING
200.	CABOT MICROELECTRONICS CORPORATION	9,330,703	POLISHING COMPOSITION FOR NICKEL-PHOSPHOROUS MEMORY DISKS
201.	CABOT MICROELECTRONICS CORPORATION	9,340,706	MIXED ABRASIVE POLISHING COMPOSITIONS
202.	CABOT MICROELECTRONICS CORPORATION	9,343,330	COMPOSITIONS FOR POLISHING ALUMINUM/COPPER AND TITANIUM IN DAMASCENE STRUCTURES
203.	CABOT MICROELECTRONICS CORPORATION	9,358,659	COMPOSITION AND METHOD FOR POLISHING GLASS
204.	CABOT MICROELECTRONICS CORPORATION	9,375,823	GROOVED CMP PADS
205.	CABOT MICROELECTRONICS CORPORATION	9,401,104	POLISHING COMPOSITION FOR EDGE ROLL-OFF IMPROVEMENT
206.	CABOT MICROELECTRONICS CORPORATION	9,409,276	CMP POLISHING PAD HAVING EDGE EXCLUSION REGION OF OFFSET CONCENTRIC GROOVE PATTERN
207.	CABOT MICROELECTRONICS CORPORATION	9,422,455	CMP COMPOSITIONS EXHIBITING REDUCED DISHING IN STI WAFER POLISHING
208.	CABOT MICROELECTRONICS CORPORATION	9,422,456	COLLOIDAL SILICA CHEMICAL MECHANICAL POLISHING COMPOSITION
209.	CABOT MICROELECTRONICS CORPORATION	9,422,457	COLLOIDAL SILICA CHEMICAL-MECHANICAL POLISHING CONCENTRATE
210.	CABOT MICROELECTRONICS CORPORATION	9,425,037	SILICON POLISHING COMPOSITIONS WITH IMPROVED PSD PERFORMANCE
211.	CABOT MICROELECTRONICS CORPORATION	9,434,859	CHEMICAL-MECHANICAL PLANARIZATION OF POLYMER FILMS
212.	CABOT MICROELECTRONICS CORPORATION	9,463,551	POLISHING PAD WITH POROUS INTERFACE AND SOLID CORE, AND RELATED APPARATUS AND METHODS

	OWNER	REGISTRATION NUMBER	DESCRIPTION
213.	CABOT MICROELECTRONICS CORPORATION	9,469,787	NICKEL PHOSPHOROUS CMP COMPOSITIONS AND METHODS
214.	CABOT MICROELECTRONICS CORPORATION	9,481,811	COMPOSITION AND METHOD FOR POLISHING MEMORY HARD DISKS EXHIBITING REDUCED EDGE ROLL-OFF
215.	CABOT MICROELECTRONICS CORPORATION	9,499,721	COLLOIDAL SILICA CHEMICAL-MECHANICAL POLISHING COMPOSITION
216.	CABOT MICROELECTRONICS CORPORATION	9,505,952	POLISHING COMPOSITION CONTAINING CERIA ABRASIVE
217.	CABOT MICROELECTRONICS CORPORATION	9,528,030	COBALT INHIBITOR COMBINATION FOR IMPROVED DISHING
218.	CABOT MICROELECTRONICS CORPORATION	9,534,147	POLISHING COMPOSITION AND METHOD FOR NICKEL-PHOSPHOROUS COATED MEMORY DISKS
219.	CABOT MICROELECTRONICS CORPORATION	9,548,211	METHOD TO SELECTIVELY POLISH SILICON CARBIDE FILMS
220.	CABOT MICROELECTRONICS CORPORATION	9,555,518	POLISHING PAD WITH MULTI-MODAL DISTRIBUTION OF PORE DIAMETERS
221.	CABOT MICROELECTRONICS CORPORATION	9,556,363	COPPER BARRIER CHEMICAL-MECHANICAL POLISHING COMPOSITION
222.	CABOT MICROELECTRONICS CORPORATION	9,566,686	COMPOSITION FOR TUNGSTEN CMP
223.	CABOT MICROELECTRONICS CORPORATION	9,567,491	TUNGSTEN CHEMICAL-MECHANICAL POLISHING COMPOSITION
224.	CABOT MICROELECTRONICS CORPORATION	9,597,768	SELECTIVE NITRIDE SLURRIES WITH IMPROVED STABILITY AND IMPROVED POLISHING CHARACTERISTICS
225.	CABOT MICROELECTRONICS CORPORATION	9,597,769	POLISHING PAD WITH POLISHING SURFACE LAYER HAVING AN APERTURE OR OPENING ABOVE A TRANSPARENT FOUNDATION LAYER
226.	CABOT MICROELECTRONICS CORPORATION	9,597,770	POLISHING PAD WITH APERTURE
227.	CABOT MICROELECTRONICS CORPORATION	9,597,777	HOMOGENEOUS POLISHING PAD FOR EDDY CURRENT END-POINT DETECTION
228.	CABOT MICROELECTRONICS CORPORATION	9,617,450	POLISHING COMPOSITION AND METHOD UTILIZING ABRASIVE PARTICLES TREATED WITH AN AMINOSILANE

	OWNER	REGISTRATION NUMBER	DESCRIPTION
229.	CABOT MICROELECTRONICS CORPORATION	9,631,122	TUNGSTEN-PROCESSING SLURRY WITH CATIONIC SURFACTANT
230.	CABOT MICROELECTRONICS CORPORATION	9,633,863	COMPOSITIONS AND METHODS FOR SELECTIVE POLISHING OF SILICON NITRIDE MATERIALS
231.	CABOT MICROELECTRONICS CORPORATION	9,649,742	POLISHING PAD HAVING POLISHING SURFACE WITH CONTINUOUS PROTRUSIONS
232.	CABOT MICROELECTRONICS CORPORATION	9,687,956	POLISHING PAD WITH OFFSET CONCENTRIC GROOVING PATTERN AND METHOD FOR POLISHING A SUBSTRATE THEREWITH
233.	CABOT MICROELECTRONICS CORPORATION	9,688,885	COBALT POLISHING ACCELERATORS
234.	CABOT MICROELECTRONICS CORPORATION	9,701,871	COMPOSITION AND METHOD FOR POLISHING BULK SILICON
235.	CABOT MICROELECTRONICS CORPORATION	9,752,057	CMP METHOD FOR SUPPRESSION OF TITANIUM NITRIDE AND TITANIUM/TITANIUM NITRIDE REMOVAL
236.	CABOT MICROELECTRONICS CORPORATION	9,758,697	POLISHING COMPOSITION CONTAINING CATIONIC POLYMER ADDITIVE
237.	CABOT MICROELECTRONICS CORPORATION	9,771,496	TUNGSTEN-PROCESSING SLURRY WITH CATIONIC SURFACTANT AND CYCLODEXTRIN
238.	CABOT MICROELECTRONICS CORPORATION	9,796,882	CMP PROCESSING COMPOSITION COMPRISING ALKYLAMINE AND CYCLODEXTRIN
239.	CABOT MICROELECTRONICS CORPORATION	9,803,106	METHODS FOR FABRICATING A CHEMICAL-MECHANICAL POLISHING COMPOSITION
240.	CABOT MICROELECTRONICS CORPORATION	9,803,109	CMP COMPOSIITION FOR SILICON NITRIDE REMOVAL
241.	CABOT MICROELECTRONICS CORPORATION	9,818,618	MULTI-LAYER POLISHING PAD FOR CMP
242.	CABOT MICROELECTRONICS CORPORATION	9,828,528	POLISHING COMPOSITION CONTAINING CERIA ABRASIVE
243.	CABOT MICROELECTRONICS CORPORATION	9,828,574	CLEANING COMPOSITION AND METHOD FOR CLEANING SEMICONDUCTOR WAFERS AFTER CMP
244.	CABOT MICROELECTRONICS CORPORATION	9,834,704	COBALT DISHING CONTROL AGENTS
245.	CABOT MICROELECTRONICS CORPORATION	9,850,402	CMP COMPOSITIONS AND METHODS FOR SELECTIVE REMOVAL OF SILICON NITRIDE

	OWNER	REGISTRATION NUMBER	DESCRIPTION
246.	CABOT MICROELECTRONICS CORPORATION	9,850,403	COBALT POLISHING ACCELERATORS
247.	CABOT MICROELECTRONICS CORPORATION	9,868,185	POLISHING PAD WITH FOUNDATION LAYER AND WINDOW ATTACHED THERETO
248.	CABOT MICROELECTRONICS CORPORATION	9,931,728	POLISHING PAD WITH FOUNDATION LAYER AND POLISHING SURFACE LAYER
249.	CABOT MICROELECTRONICS CORPORATION	9,931,729	POLISHING PAD WITH GROOVED FOUNDATION LAYER AND POLISHING SURFACE LAYER
250.	CABOT MICROELECTRONICS CORPORATION	9,944,828	SLURRY FOR CHEMICAL MECHANICAL POLISHING OF COBALT
251.	CABOT MICROELECTRONICS CORPORATION	9,951,054	CMP POROUS PAD WITH PARTICLES IN A POLYMERIC MATRIX
252.	CABOT MICROELECTRONICS CORPORATION	9.909,032	COMPOSITION AND METHOD FOR POLISHING MEMORY HARD DISKS
253.	CABOT MICROELECTRONICS CORPORATION	D640057	POLISHING PAD CARRIER
254.	QED TECHNOLOGIES INTERNATIONAL, INC.	5,951,369	SYSTEM FOR MAGNETORHEOLOGICAL FINISHING OF SUBSTRATES
255.	QED TECHNOLOGIES INTERNATIONAL, INC.	6,506,102	APPARATUS AND METHOD FOR ABRASIVE JET-FINISHING OF DEEPLY CONCAVE SURFACES USING MAGNETORHEOLOGICAL FLUID
256.	QED TECHNOLOGIES INTERNATIONAL, INC.	6,561,874	UNIFORM THIN FILMS PRODUCED BY MAGNETORHEOLOGICAL FINISHING
257.	QED TECHNOLOGIES INTERNATIONAL, INC.	6,746,310	METHOD AND APPARATUS FOR MEASURING AND CONTROLLING SOLIDS COMPOSITION OF A MAGNETORHEOLOGICAL FLUID
258.	QED TECHNOLOGIES INTERNATIONAL, INC.	6,893,322	DELIVERY SYSTEM FOR MAGNETORHEOLOGICAL FLUID
259.	QED TECHNOLOGIES INTERNATIONAL, INC.	6,955,589	METHOD FOR SELF-CALIBRATED SUB-APERTURE STITCHING FOR SURFACE FIGURE MEASUREMENT
260.	QED TECHNOLOGIES INTERNATIONAL, INC.	6,956,657	METHOD AND APPARATUS FOR FORMING A DYNAMIC MAGNETIC SEAL USING MAGNETORHEOLOGICAL FLUID
261.	QED TECHNOLOGIES INTERNATIONAL, INC.	7,156,724	METHOD FOR CALIBRATING THE GEOMETRY OF A MULTI-AXIS METROLOGY SYSTEM
262.	QED TECHNOLOGIES INTERNATIONAL, INC.	7,173,691	METHOD FOR ACCURATE HIGH-RESOLUTION MEASUREMENTS OF ASPHERIC SURFACES

	OWNER	REGISTRATION NUMBER	DESCRIPTION
263.	QED TECHNOLOGIES INTERNATIONAL, INC.	7,433,057	METHOD AND APPARATUS FOR MEASUREMENT OF MAGNETIC PERMEABILITY OF A MATERIAL
264.	QED TECHNOLOGIES INTERNATIONAL, INC.	7,557,566	METHOD AND APPARATUS FOR MEASUREMENT OF MAGNETIC PERMEABILITY OF A MATERIAL
265.	QED TECHNOLOGIES INTERNATIONAL, INC.	7,888,929	STITCHING OF NEAR-NULLED SUBAPERTURE MEASUREMENTS
266.	QED TECHNOLOGIES INTERNATIONAL, INC.	8,203,719	SYSTEM FOR MAGNETORHEOLOGICAL FINISHING OF SUBSTRATES
267.	QED TECHNOLOGIES INTERNATIONAL, INC.	8,613,640	METHOD AND APPARATUS FOR MEASUREMENT AND CONTROL OF MAGNETIC PARTICLE CONCENTRATION IN A MAGNETORHEOLOGICAL FLUID
268.	QED TECHNOLOGIES INTERNATIONAL, INC.	8,896,293	SYSTEM FOR MAGNETORHEOLOGICAL FINISHING OF A SUBSTRATE
269.	QED TECHNOLOGIES INTERNATIONAL, INC.	8,944,883	INTEGRATED WAVEFRONT SENSOR AND PROFILOMETER
270.	QED TECHNOLOGIES INTERNATIONAL, INC.	9,097,612 B2	MAGNETORHEOLOGICAL FLUID FOR ULTRASMOOTH POLISHING
271.	QED TECHNOLOGIES INTERNATIONAL, INC.	9,157,010	COBALT INHIBITOR COMBINATION FOR IMPROVED DISHING
272.	Flowchem, Ltd. (n/k/a Flowchem, LLC)	8,669,304	DRAG REDUCING COMPOSITIONS AND METHODS OF MANUFACTURE AND USE
273.	Flowchem, Ltd. (n/k/a Flowchem, LLC)	8,933,149	Drag Reducing Compositions and Methods of Manufacture and Use
274.	Flowchem, Ltd. (n/k/a Flowchem, LLC)	9,416,331	Drag Reducing Compositions and Methods of Manufacture and Use
275.	Flowchem, Ltd. (n/k/a Flowchem, LLC)	9,267,094	Drag Reducing Compositions and Methods of Manufacture and Use
276.	KMG Electronic Chemicals, Inc.	6,125,871	VALVE ASSEMBLY WITH FLUSH AND SAMPLE CAPABILITY
277.	KMG Electronic Chemicals, Inc.	6,162,370	COMPOSITION AND METHOD FOR SELECTIVELY ETCHING A SILICON NITRIDE FILM
278.	KMG Electronic Chemicals, Inc.	6,303,514	Composition and method for selectively etching a silicon nitride film

	OWNER	REGISTRATION NUMBER	DESCRIPTION
279.	KMG Electronic Chemicals, Inc.	6,358,899	Cleaning compositions and use thereof containing ammonium hydroxide and fluorosurfactant
280.	MPower Specialty Chemicals LLC	5,869,570 (Expired)	COMPOSITION OF AND PROCESS FOR FORMING POLYALPHAOLEFIN DRAG REDUCING AGENTS
281.	MPower Specialty Chemicals LLC	5,951,946 (Expired)	COMPOSITION AND METHOD OF REMOVING ODORS
282.	MPower Specialty Chemicals LLC	6,015,779	METHODS FOR FORMING AMORPHOUS ULTRA-HIGH MOLECULAR WEIGHT POLYALPHAOLEFIN DRAG REDUCING AGENTS
283.	MPower Specialty Chemicals LLC	6,162,773	METHODS FOR FORMING AMORPHOUS ULTRA-HIGH MOLECULAR WEIGHT POLYALPHAOLEFIN DRAG REDUCING AGENTS USING A HALOHYDROCARBON
284.	MPower Specialty Chemicals LLC	6,242,395	METHODS FOR FORMING AMORPHOUS ULTRA-HIGH MOLECULAR WEIGHT POLYALPHAOLEFIN DRAG REDUCING AGENTS USING NON-METALLOCENE CATALYSTS AND ALKYLALUMINOXANE
285.	MPower Specialty Chemicals LLC	6,730,750	METHODS FOR FORMING AMORPHOUS ULTRA-HIGH MOLECULAR WEIGHT POLYOLEFINS FOR USE AS DRAG REDUCING AGENTS
286.	MPower Specialty Chemicals LLC	6,730,752	METHODS FOR FORMING AMORPHOUS ULTRA-HIGH MOLECULAR WEIGHT POLYOLEFINS AND DRAG REDUCING COMPOSITIONS COMPRISING AMORPHOUS ULTRA-HIGH MOLECULAR WEIGHT POLYOLEFINS
287.	MPower Specialty Chemicals LLC	6,815,011	ALPHA OLEFIN MONOMER PARTITIONING AGENTS FOR DRAG REDUCING AGENTS AND METHODS OF FORMING DRAG REDUCING AGENTS USING ALPHA OLEFIN MONOMER PARTITIONING AGENTS
288.	MPower Specialty Chemicals LLC	6,989,357	ALCOHOL ABSORBED POLYALPHAOLEFIN DRAG REDUCING AGENTS
289.	MPower Specialty Chemicals LLC	7,012,046	DRAG REDUCING AGENT SLURRIES HAVING ALFOL ALCOHOLS AND PROCESSES FOR FORMING DRAG REDUCING AGENT SLURRIES HAVING ALFOL ALCOHOLS
290.	MPower Specialty Chemicals LLC	7,534,403	BULK POLYMERIZATION REACTORS
291.	MPower Specialty Chemicals LLC	7,582,708	BULK POLYMERIZATION REACTOR METHODS
292.	MPower Specialty Chemicals LLC	8,105,547	BULK POLYMERIZATION REACTORS

	OWNER	REGISTRATION NUMBER	DESCRIPTION
293.	MPower Specialty Chemicals LLC	8,106,114	DRAG REDUCING AGENT AND METHOD OF USE
294.	MPower Specialty Chemicals LLC	8,110,150	BULK POLYMERIZATION REACTORS FOR PRODUCING DRAG REDUCER

U.S. Patent Applications:

	OWNER	APPLICATION NUMBER	DESCRIPTION
1.	CABOT MICROELECTRONICS CORPORATION	12/673,057	POLISHING PAD
2.	CABOT MICROELECTRONICS CORPORATION	13/829,990	POLISHING PAD HAVING POLISHING SURFACE WITH CONTINUOUS PROTRUSIONS HAVING TAPERED SIDEWALLS
3.	CABOT MICROELECTRONICS CORPORATION	13/955,398	LOW DENSITY POLISHING PAD
4.	CABOT MICROELECTRONICS CORPORATION	14/094,921	CMP COMPOSITIONS AND METHODS FOR POLISHING NICKEL-PHOSPHOROUS SURFACES
5.	CABOT MICROELECTRONICS CORPORATION	14/209,110	COMPOSITION AND METHOD FOR POLISHING POLYSILICON
6.	CABOT MICROELECTRONICS CORPORATION	14/562,589	METHODS FOR PRODUCING IN-SITU GROOVES IN CHEMICAL MECHANICAL PLANARIZATION (CMP) PADS, AND NOVEL CMP PAD DESIGNS
7.	CABOT MICROELECTRONICS CORPORATION	14/611,064	LOW DENSITY POLISHING PAD
8.	CABOT MICROELECTRONICS CORPORATION	14/639,434	COMPOSITIONS AND METHODS FOR CMP OF TUNGSTEN MATERIALS
9.	CABOT MICROELECTRONICS CORPORATION	14/686,988	COMPOSITION AND METHOD FOR POLISHING MOLYBDENUM
10.	CABOT MICROELECTRONICS CORPORATION	14/743,583	CMP SLURRY COMPOSITIONS AND METHODS FOR ALUMINUM POLISHING
11.	CABOT MICROELECTRONICS CORPORATION	14/823,956	SOFT POLISHING PAD FOR POLISHING A SEMICONDUCTOR SUBSTRATE
12.	CABOT MICROELECTRONICS CORPORATION	14/838,460	COMPOSITION AND METHOD FOR POLISHING A SAPPHIRE SURFACE
13.	CABOT MICROELECTRONICS CORPORATION	14/875,513	POLISHING PAD WITH CONCENTRIC OR APPROXIMATELY CONCENTRIC POLYGON GROOVE PATTERN
14.	CABOT MICROELECTRONICS CORPORATION	14/919,404	CORROSION INHIBITORS AND RELATED COMPOSITIONS AND METHODS
15.	CABOT MICROELECTRONICS CORPORATION	15/042,777	CUSTOMIZED POLISH PADS FOR CMP AND METHODS OF FABRICATION AND USE THEREOF
16.	CABOT MICROELECTRONICS CORPORATION	15/056,198	POLISHING COMPOSITION CONTAINING CERIA PARTICLES AND METHOD OF USE
17.	CABOT MICROELECTRONICS CORPORATION	15/091,275	CMP COMPOSITION AND METHOD FOR POLISHING RIGID DISKS

	OWNER	APPLICATION NUMBER	DESCRIPTION
18.	CABOT MICROELECTRONICS CORPORATION	15/252,567	METHODS AND COMPOSITIONS FOR PROCESSING DIELECTRIC SUBSTRATE
19.	CABOT MICROELECTRONICS CORPORATION	15/273,855	POLYURETHANE CMP PADS HAVING A HIGH MODULUS RATIO
20.	CABOT MICROELECTRONICS CORPORATION	15/303,696	CMP POLISHING PAD WITH COLUMNAR STRUCTURE AND METHODS RELATED THERETO
21.	CABOT MICROELECTRONICS CORPORATION	15/346,835	POLISHING COMPOSITION AND METHOD UTILIZING ABRASIVE PARTICLES TREATED WITH AN AMINOSILANE
22.	CABOT MICROELECTRONICS CORPORATION	15/398,933	COMPOSITION AND METHOD FOR POLISHING SILICON CARBIDE
23.	CABOT MICROELECTRONICS CORPORATION	15/399,810	METHOD OF POLISHING A LOW-K SUBSTRATE
24.	CABOT MICROELECTRONICS CORPORATION	15/414,786	POLISHING COMPOSITION COMPRISING CATIONIC POLYMER ADDITIVE
25.	CABOT MICROELECTRONICS CORPORATION	15/433,068	METHOD OF POLISHING GROUP III-V MATERIALS
26.	CABOT MICROELECTRONICS CORPORATION	15/479,779	POLISHING PAD HAVING POLISHING SURFACE WITH CONTINUOUS PROTRUSIONS
27.	CABOT MICROELECTRONICS CORPORATION	15/564,605	DIAMOND-BASED SLURRIES WITH IMPROVED SAPPHIRE REMOVAL RATE AND SURFACE ROUGHNESS
28.	CABOT MICROELECTRONICS CORPORATION	15/615,591	CHEMICAL-MECHANICAL PROCESSING SLURRY AND METHODS FOR PROCESSING A NICKEL SUBSTRATE SURFACE
29.	CABOT MICROELECTRONICS CORPORATION	15/629,487	POLISHING COMPOSITION COMPRISING AN AMINE-CONTAINING SURFACTANT
30.	CABOT MICROELECTRONICS CORPORATION	15/649,378	ALTERNATIVE OXIDIZING AGENTS FOR COBALT CMP
31.	CABOT MICROELECTRONICS CORPORATION	15/684,470	SYSTEMS FOR MIXING A LIQUID AND RELATED METHODS
32.	CABOT MICROELECTRONICS CORPORATION	15/706,192	NITRIDE INHIBITORS FOR HIGH SELECTIVITY OF TiN-SiN CMP APPLICATIONS
33.	CABOT MICROELECTRONICS CORPORATION	15/723,886	SURFACE TREATED ABRASIVE PARTICLES FOR TUNGSTEN BUFF APPLICATIONS
34.	CABOT MICROELECTRONICS CORPORATION	15/784,949	CMP COMPOSITIONS SELECTIVE FOR OXIDE AND NITRIDE WITH IMPROVED DISHING AND PATTERN SELECTIVITY
35.	CABOT MICROELECTRONICS CORPORATION	15/817,959	COMPOSITION AND METHOD FOR POLISHING MEMORY HARD DISKS EXHIBITING REDUCED SURFACE SCRATCHING
36.	CABOT MICROELECTRONICS CORPORATION	15/825,305	COMPOSITION AND METHOD FOR REMOVING RESIDUE FROM CHEMICAL-MECHANICAL PLANARIZATION SUBSTRATE
37.	CABOT MICROELECTRONICS CORPORATION	15/864,720	TUNGSTEN BUFF POLISHING COMPOSITIONS WITH IMPROVED TOPOGRAPHY
38.	CABOT MICROELECTRONICS CORPORATION	15/866,008	TUNGSTEN BULK POLISHING METHOD WITH IMPROVED TOPOGRAPHY
39.	CABOT MICROELECTRONICS CORPORATION	15/875,773	COATED COMPRESSIVE SUBPAD FOR CHEMICAL MECHANICAL POLISHING

	OWNER	APPLICATION NUMBER	DESCRIPTION
40.	CABOT MICROELECTRONICS CORPORATION	15/920,813	CMP COMPOSITIONS CONTAINING POLYMER COMPLEXES AND AGENTS FOR STI APPLICATIONS
41.	CABOT MICROELECTRONICS CORPORATION	15/934,219	SELF-STOPPING POLISHING COMPOSITION AND METHOD FOR BULK OXIDE PLANARIZATION
42.	CABOT MICROELECTRONICS CORPORATION	15/951,358	CHEMICAL-MECHANICAL PROCESSING SLURRY AND METHODS
43.	CABOT MICROELECTRONICS CORPORATION	15/951,598	CHEMICAL-MECHANICAL PROCESSING SLURRY AND METHODS FOR PROCESSING A NICKEL SUBSTRATE SURFACE
44.	CABOT MICROELECTRONICS CORPORATION	16/000,062	COMPOSITION AND METHOD FOR POLISHING MEMORY HARD DISKS EXHIBITING REDUCED EDGE ROLL OFF
45.	CABOT MICROELECTRONICS CORPORATION	16/018,281	METHODS AND COMPOSITIONS FOR PROCESSING DIELECTRIC SUBSTRATE
46.	CABOT MICROELECTRONICS CORPORATION	16/131,180	COMPOSITION FOR TUNGSTEN CMP
47.	CABOT MICROELECTRONICS CORPORATION	PCT/US2016/053283	POLYURETHANE CMP PADS HAVING A HIGH MODULUS RATIO
48.	CABOT MICROELECTRONICS CORPORATION	PCT/US2016/058042	TUNGSTEN-PROCESSING SLURRY WITH CATIONIC SURFACTANT
49.	CABOT MICROELECTRONICS CORPORATION	PCT/US2017/036203	CHEMICAL-MECHANICAL PROCESSING SLURRY AND METHODS FOR PROCESSING A NICKEL SUBSTRATE SURFACE
50.	CABOT MICROELECTRONICS CORPORATION	PCT/US2017/038584	POLISHING COMPOSITION COMPRISING AN AMINE-CONTAINING SURFACTANT
51.	CABOT MICROELECTRONICS CORPORATION	PCT/US2017/041988	ALTERNATIVE OXIDIZING AGENTS FOR COBALT CMP
52.	CABOT MICROELECTRONICS CORPORATION	PCT/US2017/056809	CMP COMPOSITIONS SELECTIVE FOR OXIDE AND NITRIDE WITH IMPROVED DISHING AND PATTERN SELECTIVITY
53.	CABOT MICROELECTRONICS CORPORATION	PCT/US2017/063586	COMPOSITION AND METHOD FOR REMOVING RESIDUE FROM CHEMICAL-MECHANICAL PLANARIZATION SUBSTRATE
54.	CABOT MICROELECTRONICS CORPORATION	PCT/US2017/067947	COMPOSITION AND METHOD FOR POLISHING SILICON CARBIDE
55.	CABOT MICROELECTRONICS CORPORATION	PCT/US2018/051012	COMPOSITION FOR TUNGSTEN CMP
56.	CABOT MICROELECTRONICS CORPORATION	PCT/US2018/054079	SURFACE TREATED ABRASIVE PARTICLES FOR TUNGSTEN BUFF APPLICATIONS
57.	CABOT MICROELECTRONICS CORPORATION	PCT/US2018/057478	COMPOSITION AND METHOD FOR POLISHING MEMORY HARD DISKS EXHIBITING REDUCED SURFACE SCRATCHING
58.	CABOT MICROELECTRONICS CORPORATION	PCTUS1824067	SELF-STOPPING POLISHING COMPOSITION AND METHOD FOR BULK OXIDE PLANARIZATION
59.	CABOT MICROELECTRONICS CORPORATION	PCTUS1827234	CHEMICAL-MECHANICAL PROCESSING SLURRY AND METHODS
60.	CABOT MICROELECTRONICS CORPORATION	PCTUS1827281	CHEMICAL-MECHANICAL PROCESSING SLURRY AND METHODS FOR PROCESSING A NICKEL SUBSTRATE SURFACE

	OWNER	APPLICATION NUMBER	DESCRIPTION
61.	CABOT MICROELECTRONICS CORPORATION	PCTUS1846429	NITRIDE INHIBITORS FOR HIGH SELECTIVITY OF TIN-SIN CMP APPLICATIONS

Release of Notice of Grant of Security Interest in Patents recorded April 30, 2021 at Reel/Frame 056104/0979

U.S. Federally Issued or Applied for Patents Owned by New Subsidiary

Title	**Country**	**Serial Number** **Filing Date**	**Patent Number** **Issue Date**	**Status** **Deadlines**
Cleaning System, Device and Method	US	09/624,750 7/24/2000	6,777,966 8/17/2004	Issued. Claims cover basic cleaning material Expires 7/24/2020 + PTA Expired 2/17/2021
Cleaning System, Device and Method	US- CON	10/825,718 4/16/2004	7,202,683 4/10/2007	Issued. Claims cover basic cleaning material Expires 7/24/2020+ PTA Expired 7/24/2020
Working Surface Cleaning System and Method	US- CIP	13/961,127 8/7/2013	9,833,818 12/5/2017	Issued.
Working Surface Cleaning System and Method	US CON	15/818,386 11/20/2017	10,239,099 3/26/2019	Issued.
Working Surface Cleaning System and Method	US CON	16/290,789 3/1/2019	10,406,568 9/10/2019	Issued.
Working Surface Cleaning System and Method	US CON	16/438,162 6/11/2019	N/A N/A	Pending.
Apparatus, Device and Methods for Cleaning Tester Interface Contact Elements and Support Hardware	US	12/630,714 12/3/2009	8,371,316 2/12/2013	Issued.
Apparatus, Device and Methods for Cleaning Tester Interface Contact Elements and Support Hardware	US – DIV1	13/290,015 11/4/2011	8,801,869 8/12/2014	Issued.
Apparatus, Device and Methods for Cleaning Tester Interface Contact Elements and Support Hardware	US – DIV2	13/290,017 11/4/2011	8,790,466 7/29/2014	Issued.
Apparatus, Device and Methods for Cleaning Tester Interface Contact Elements and Support Hardware	US – CON	14/445,003 7/28/2014	10,195,648 2/5/2019	Issued.
Apparatus, Device and Methods for Cleaning Tester Interface Contact Elements and Support Hardware	US – CON	16/228,664 12/20/2018	N/A N/A	Pending.

Title	Country	Serial Number Filing Date	Patent Number Issue Date	Status Deadlines
Semiconductor Wire Bonding Machine Cleaning Device and Method	US	15/495,873 4/23/2017	9,825,000 11/21/2017	Issued.
Semiconductor Wire Bonding Machine Cleaning Device and Method	US – CON	15/723,151 10/2/2017	10,361,169 7/23/2019	Issued.
Novel Material and Hardware to Automatically Clean Flexible Electronics Web Rolls	US	16/283,592 2/22/2019	10,843,885 11-24/2020	Issued.
Novel Material and Hardware to Automatically Clean Flexible Electronics Web Rolls	US	16/283,603 2/22/2019	N/A N/A	Pending.
Novel Material and Hardware to Automatically Clean Flexible Electronics Web Rolls	US	16/283,607 2/22/2019	10,717,618 7/21/2020	Issued.
Novel Material and Hardware to Automatically Clean Flexible Electronics Web Rolls	US	16/283,613 2/22/2019	N/A N/A	Pending.
Pick and Place Machine Cleaning System and Method	US	16/460,877 7/2/2019	N/A N/A	Pending.
Pick and Place Machine Cleaning System and Method	US	16/460,918 7/2/2019	N/A N/A	Pending.
Pick and Place Machine Cleaning System and Method	US	16/460,929 7/2/2019	N/A N/A	Pending.
Pick and Place Machine Cleaning System and Method	US	16/460,935 7/2/2019	10,792,713 10-6-2020	Issued
Pick and Place Machine Cleaning System and Method	US DIV	16/794,068 2/18/2020	N/A N/A	Pending.
System and Method for Cleaning Contact Elements and Support Hardware Using Functionalized Surface Microfeatures	US	16/684,453 11/14/2019	N/A N/A	Pending.
Functionalized Surface Microfeatures for Wire Bonders	US CIP	16/855,841 4/22/2020	N/A N/A	Pending.
Heat Conductive Wafer	US	16/872,292 5-11-2020	N/A N/A	Allowed.
Wafer Manufacturing Cleaning Apparatus, Process and Method of Use	US	13/725,827 12/21/2012	Granted 10,002,776 (6/19/2018)	Granted. Expires (10/7/2030); Assignment to be recorded with USPTO

Title	Country	Serial Number Filing Date	Patent Number Issue Date	Status Deadlines
				Assignment recorded 3/4/21 at Reel 055500 Frame 0329
Wafer Manufacturing Cleaning Apparatus, Process and Method of Use	US	13/971,619 8/20/2013	Granted 9,595,456 (3/14/2017)	Granted. Expires (4/14/2030); Assignment to be recorded with USPTO Assignment recorded 3/4/21 at Reel 055500 Frame 0329
Wafer Manufacturing Cleaning Apparatus, Process and Method of Use	US	15/419,840 1/30/2017	Granted 10,109,504 (10/23/2018)	Granted. Expires (4/14/2030); Assignment to be recorded with USPTO Assignment recorded 3/4/21 at Reel 055500 Frame 0329
Wafer Manufacturing Cleaning Apparatus, Process and Method of Use	US	16/136,965 9/20/2018	Granted 10,741,420 (8/11/2020)	Granted. Expires (4/14/2030); Assignment to be recorded with USPTO Assignment recorded 3/4/21 at Reel 055500 Frame 0329
Wafer Manufacturing Cleaning Apparatus, Process and Method of Use	US	16/895,106 6/8/2020	Granted 10,896,828 (1/19/2021)	Granted. Expires (4/14/2030); Assignment to be recorded with USPTO Assignment recorded 3/4/21 at Reel 055500 Frame 0329

Release of Notice of Grant of Security Interest in Patents recorded July 2, 2021 at Reel/Frame 056752/0645

U.S. Patents and Applications:

	Owner	Patent Title	Appl. No. Filing Date	Patent No. Issue Date
1.	CMC Materials, Inc.	Polishing Composition And Method Utilizing Abrasive Particles Treated With An Aminosilane	16664235 10/25/2019	11034862 06/15/2021
2.	CMC Materials, Inc.	Polishing Composition And Method With High Selectivity For Silicon Nitride And Polysilicon Over Silicon Oxide	17076989 10/22/2020	N/A
3.	CMC Materials, Inc.	Composition And Method For Dielectric CMP	17077070 10/22/2020	N/A
4.	CMC Materials, Inc.	Composition And Method For Dielectric CMP	17077155 10/22/2020	N/A
5.	CMC Materials, Inc.	Composition And Method For Silicon Oxide And Carbon Doped Silicon Oxide CMP	17077295 10/22/2020	N/A
6.	CMC Materials, Inc.	Self-Stopping Polishing Composition And Method	17077414 10/22/2020	N/A
7.	CMC Materials, Inc.	Composition And Method For Selective Oxide CMP	17077485 10/22/2020	N/A
8.	CMC Materials, Inc.	Composition And Method For Polysilicon CMP	17009961 09/02/2020	N/A
9.	CMC Materials, Inc.	Method To Increase Barrier Film Removal Rate In Bulk Tungsten Slurry	16513404 07/16/2019	N/A
10.	CMC Materials, Inc.	Polishing Pad Employing Polyamine And Cyclohexanedimethanol Curatives	16923688 07/08/2020	N/A
11.	CMC Materials, Inc.	Chemical Mechanical Planarization Pads With Constant Groove Volume	16868755 05/07/2020	N/A
12.	CMC Materials, Inc.	Chemical Mechanical Planarization Pads Via Vat-Based Production	16868965 05/07/2020	N/A
13.	CMC Materials, Inc.	Surface Coated Abrasive Particles For Tungsten Buff Applications	16849021 04/15/2020	N/A
14.	CMC Materials, Inc.	Additives To Improve Particle Dispersion For CMP Slurry	16826409 03/23/2020	N/A
15.	CMC Materials, Inc.	Dual Additive Composition For Polishing Memory Hard Disks Exhibiting Edge Roll Off	16729905 12/30/2019	N/A
16.	CMC Materials, Inc.	Oxidizer Free Slurry For Ruthenium CMP	16706991 12/09/2019	N/A
17.	CMC Materials, Inc.	Composition And Method For Silicon Nitride CMP	16208779 12/04/2018	N/A
18.	CMC Materials, Inc.	Composition And Method For Cobalt CMP	16208703 12/04/2018	N/A
19.	CMC Materials, Inc.	Composition And Method For Polishing Silicon Carbide	16389097 04/19/2019	N/A
20.	CMC Materials, Inc.	Composition And Method For Copper Barrier CMP	16208797 12/04/2018	10988635 04/27/2021
21.	CMC Materials, Inc.	COMPOSITION AND METHOD FOR METAL CMP	16208742 12/04/2018	10968366 04/06/2021
22.	CMC Materials, Inc.	Self-Stopping Polishing Composition And Method For Bulk Oxide Planarization	16797438 02/21/2020	10920107 02/16/2021
23.	CMC Materials, Inc.	Self-Stopping Polishing Composition And Method For Bulk Oxide Planarization	16271508 02/08/2019	10619076 04/14/2020

	Owner	Patent Title	Appl. No. Filing Date	Patent No. Issue Date
24.	CMC Materials, Inc.	Composition For Tungsten CMP	16236962 12/31/2018	10676647 06/09/2020
25.	CMC Materials, Inc.	Safety Closures And Pumping Systems	14577453 12/19/2014	10184469 01/22/2019

SCHEDULE II

Release of Notice of Grant of Security Interest in Trademarks recorded November 16, 2018 at Reel/Frame 6483/0177

Trademarks

UNITED STATES TRADEMARKS:

U.S. Trademark Registrations:

	OWNER	REGISTRATION NUMBER	TRADEMARK
1.	Cabot Microelectronics Corporation	4,372,801	ELEMENT
2.	Cabot Microelectronics Corporation	2,363,181	EPIC
3.	Cabot Microelectronics Corporation	2,517,587	ICUE
4.	Cabot Microelectronics Corporation	4,613,239	IDIEL
5.	Cabot Microelectronics Corporation	2,632,288	LUSTRA
6.	Cabot Microelectronics Corporation	5,354,755	MEDEA
7.	Cabot Microelectronics Corporation	3,702,810	NEXPLANAR
8.	Cabot Microelectronics Corporation	1,704,025	SEMI-SPERSE
9.	Cabot Microelectronics Corporation	1,917,115	SEMI-SPERSE
10.	Cabot Microelectronics Corporation	3,103,184	SILECT
11.	Cabot Microelectronics Corporation	3,623,364	TRANSELE
12.	Cabot Microelectronics Corporation	3,456,932	WIN
13.	Epoch Material Co., Ltd.	3,451,884	EPOCH
14.	Epoch Material Co., Ltd.	2,499,905	ETERPOL
15.	QED Technologies International, Inc.	3,737,365	ASI
16.	QED Technologies International, Inc.	2,827,173	MRF
17.	QED Technologies International, Inc.	4,303,897	QED OPTICS
18.	QED Technologies International, Inc.	2,777,617	QED TECHNOLOGIES
19.	QED Technologies International, Inc.	4,270,737	Q-FLEX
20.	Flowchem, Ltd. (n/k/a Flowchem, LLC)	2971771	TURBOFLO
21.	KMG Electronic Chemicals, Inc.	1851237	CLEANROOM
22.	KMG Electronic Chemicals, Inc.	1705722	GIGABIT
23.	KMG Electronic Chemicals, Inc.	3949164	NANO-STRIP
24.	KMG Electronic Chemicals, Inc.	3306579	NANO-STRIP
25.	KMG Electronic Chemicals, Inc.	1533823	PARTICU-LO
26.	KMG Electronic Chemicals, Inc.	2189410	PARTICU-LO LTM
27.	KMG Electronic Chemicals, Inc.	1870262	TERABIT
28.	KMG Electronic Chemicals, Inc.	1907795	ULTRA-ETCH
29.	KMG-Bernuth, Inc.	0821851	BUENO
30.	KMG Ultra Pure Chemicals Limited	4697731 (66A)	OMNI
31.	KMG Ultra Pure Chemicals Limited	4177579 (66A)	OMNICU

	OWNER	REGISTRATION NUMBER	TRADEMARK
32.	KMG-Bernuth, Inc.	0821805	DACONATE
33.	MPower Specialty Chemicals LLC	2994247	HIPR
34.	MPower Specialty Chemicals LLC	2243649	X-PAND
35.	Sealweld (USA), Inc.	2142260	SEALWELD
36.	Sealweld (USA), Inc.	5514442	FLOW WOLF
37.	Sealweld (USA), Inc.	5514443	CHAMELEON SEAL
38.	Sealweld (USA), Inc.	5520231	ACTIV-8
39.	Sealweld (USA), Inc.	5498636	VALVE CLEANER PLUS
40.	Valves Incorporated of Texas	4053560	VIPER

U.S. Trademark Applications:

None.

Release of Notice of Grant of Security Interest in Trademarks recorded April 30, 2021 at Reel/Frame 7276/0107

U.S. Federally Registered or Applied for Trademarks Owned by New Subsidiary

Mark	Image	Country	Application Date	Application Number	Registration Date	Registration Number	Goods and Services	Status
PROBE REFRESH[1]	Probe Refresh	USPTO	**App** 13-SEP-2017	**App** 87606969	**Reg** 31-DEC-2019	**Reg** 5947138	**INT. CL. 3** CLEANING MATERIALS BEING ABRASIVE SHEETS OF POLYMER FILM EMBEDDED WITH ABRASIVES FOR CLEANING OF ELECTRONIC COMPONENT AND CIRCUIT MATERIALS	Registered
PROBE VERTICAL	Probe Vertical	USPTO	**App** 13-SEP-2017	**App** 87606989	**Reg** 31-DEC-2019	**Reg** 5947139	**INT. CL. 3** CLEANING MATERIALS BEING ABRASIVE SHEETS OF POLYMER FILM EMBEDDED WITH ABRASIVES FOR CLEANING OF ELECTRONIC COMPONENT AND CIRCUIT MATERIALS	Registered
ETCH CLEAN	ETCH CLEAN	USPTO	**App** 27-SEP-2013	**App** 86077492	**Reg** 04-FEB-2014	**Reg** 4479239	**INT. CL. 3** CLEANER FOR USE ON INTEGRATED CIRCUITS TO COLLECT AND REMOVE DEBRIS GENERATED DURING	Registered Supplemental Register

[1] Record ownership for all trademarks and trademark applications are in prior name of International Test Solutions, Inc. Company will be filing assignment to update record ownership to International Test Solutions, LLC

Mark	Image	Country	Application Date	Application Number	Registration Date	Registration Number	Goods and Services	Status
							MANUFACTURING; CLEANING AGENTS AND PREPARATIONS	
STAGE CLEAN[2]	STAGE CLEAN	USPTO	**App** 13-AUG-2013	**App** 86037041	**Reg** 22-APR-2014	**Reg** 4517513	**INT. CL. 3** CLEANER FOR USE ON INTEGRATED CIRCUITS TO COLLECT AND REMOVE DEBRIS GENERATED DURING MANUFACTURING; CLEANING AGENTS AND PREPARATIONS	Registered
CCW	CCW	USPTO	**App** 08-MAY-2009	**App** 77733035	**Reg** 15-DEC-2009	**Reg** 3725048	**INT. CL. 3** CLEANING PREPARATIONS FOR COLLECTING AND/OR REMOVING DEBRIS GENERATED DURING TESTING OF INTEGRATED CIRCUITS	Renewed (Registered)
SCD	SCD	USPTO	**App** 08-MAY-2009	**App** 77733038	**Reg** 15-DEC-2009	**Reg** 3725049	**INT. CL. 3** CLEANING PREPARATIONS FOR COLLECTING AND/OR REMOVING DEBRIS GENERATED DURING TESTING OF INTEGRATED CIRCUITS	Renewed (Registered)

[2] Record ownership for all trademarks and trademark applications are in prior name of International Test Solutions, Inc. Company to file assignment to update record ownership to International Test Solutions, LLC

Mark	Image	Country	Application Date	Application Number	Registration Date	Registration Number	Goods and Services	Status
TCC	TCC	USPTO	**App** 08-MAY-2009	**App** 77733039	**Reg** 20-JUL-2010	**Reg** 3820328	**INT. CL. 3** CLEANING PREPARATIONS FOR COLLECTING AND/OR REMOVING DEBRIS GENERATED DURING TESTING OF INTEGRATED CIRCUITS FOR USE BY INDIVIDUAL DEVICE MANUFACTURERS SUCH AS CONSTRUCTORS, FABRICATORS OR ASSEMBLERS OF END-PRODUCT ELECTRONIC DEVICES IN ORDER TO PREPARE FOR THE TESTING OF THE PERFORMANCE OF THE COMPONENT INTEGRATED CIRCUITS FOR THEIR PRODUCTS	Renewed (Registered)
PROBE POLISH	PROBE POLISH	USPTO	**App** 18-DEC-2008	**App** 77636417	**Reg** 28-JUL-2009	**Reg** 3660513	**INT. CL. 3** CLEANING MATERIAL COMPRISED OF POLYMER CHAINS USED TO COLLECT AND/OR REMOVE DEBRIS GENERATED DURING TESTING OF INTEGRATED CIRCUITS	Renewed (Registered)Section 2(F)

Mark	Image	Country	Application Date	Application Number	Registration Date	Registration Number	Goods and Services	Status
PROBE SCRUB	PROBE SCRUB	USPTO	**App** 18-DEC-2008	**App** 77636420	**Reg** 28-JUL-2009	**Reg** 3660514	**INT. CL. 3** CLEANING MATERIAL USED TO COLLECT AND/OR REMOVE DEBRIS GENERATED DURING TESTING OF INTEGRATED CIRCUITS	Renewed (Registered) Section 2(F)
PROBE CLEAN[3]	PROBE CLEAN	USPTO	**App** 15-DEC-2008	**App** 77633420	**Reg** 28-JUL-2009	**Reg** 3660499	**INT. CL. 3** CLEANING MATERIAL USED TO COLLECT AND/OR REMOVE DEBRIS GENERATED DURING TESTING OF INTEGRATED CIRCUITS	Renewed (Registered) Section 2(F)
PROBE LAP	PROBE LAP	USPTO	**App** 09-AUG-2006	**App** 78948800	**Reg** 12-JUN-2007	**Reg** 3251735	**INT. CL. 3** CLEANING PREPARATIONS FOR CLEANING AND REMOVING DEBRIS GENERATED DURING TESTING OF INTEGRATED CIRCUITS	Renewed (Registered)
PROBE FORM		USPTO	**App** 23-JUL-2001	**App** 76289852	**Reg** 29-OCT-2002	**Reg** 2642325	**INT. CL. 3** CLEANING MATERIAL COMPRISED OF POLYMER CHAINS USED TO COLLECT AND/OR REMOVE DEBRIS GENERATED DURING TESTING OF INTEGRATED CIRCUITS	Renewed (Registered)

[3] Record ownership for all trademarks and trademark applications are in prior name of International Test Solutions, Inc. Company will be filing assignment to update record ownership to International Test Solutions, LLC

Mark	Image	Country	Application Date	Application Number	Registration Date	Registration Number	Goods and Services	Status
PROBE POLISH		USPTO	**App** 23-JUL-2001	**App** 76289858	**Reg** 20-AUG-2002	**Reg** 2610970	**INT. CL. 3** CLEANING MATERIAL COMPRISED OF POLYMER CHAINS USED TO COLLECT AND/OR REMOVE DEBRIS GENERATED DURING TESTING OF INTEGRATED CIRCUITS	Renewed (Registered) Supplemental Register
INTERNATIONAL TEST SOLUTIONS		USPTO	**App** 23-JUL-2001	**App** 76289860	**Reg** 19-NOV-2002	**Reg** 2651534	**INT. CL. 3** CLEANING MATERIAL COMPRISED OF POLYMER CHAINS USED TO COLLECT AND/OR REMOVE DEBRIS GENERATED DURING TESTING OF INTEGRATED CIRCUITS	Renewed (Registered) Partial Section 2(F)
PROBE CLEAN		USPTO	**App** 23-JUL-2001	**App** 76289916	**Reg** 23-JUL-2002	**Reg** 2599807	**INT. CL. 3** CLEANING MATERIAL COMPRISED OF POLYMER CHAINS USED TO COLLECT AND/OR REMOVE DEBRIS GENERATED DURING TESTING OF INTEGRATED CIRCUITS	Renewed (Registered) Supplemental Register
PROBE SCRUB		USPTO	**App** 23-JUL-2001	**App** 76289917	**Reg** 23-JUL-2002	**Reg** 2599808	**INT. CL. 3** CLEANING MATERIAL COMPRISED OF POLYMER CHAINS USED TO COLLECT AND/OR REMOVE DEBRIS GENERATED DURING TESTING OF	Renewed (Registered) Supplemental Register

Mark	Image	Country	Application Date	Application Number	Registration Date	Registration Number	Goods and Services	Status
							INTEGRATED CIRCUITS	

Release of Notice of Grant of Security Interest in Trademarks recorded July 2, 2021 at Reel/Frame 7345/0418

U.S. Trademarks and Applications:

	Owner	Trademark	Appl. No. Filing Date	Reg. No. Reg. Date
1.	CMC Materials, Inc.	SEALVALVE	87978962 09/30/2016	6010732 03/17/2020
2.	CMC Materials, Inc.	EQUA-LUBE EIGHTY	87219669 10/28/2016	5944473 12/24/2019
3.	CMC Materials, Inc.	TOTAL-LUBE #911	87219660 10/28/2016	5638495 12/25/2018
4.	CMC Materials, Inc.	SEALVALVE	87189937 09/30/2016	5969362 01/21/2020
5.	CMC Materials, Inc.	SEALWELD	87189442 09/30/2016	6085978 06/23/2020
6.	CMC Materials, Inc.	GRIZZLY SEAL	87189421 09/30/2016	5807265 07/16/2019
7.	CMC Materials, Inc.	VALVEPRO	87189409 09/30/2016	5938369 12/17/2019
8.	CMC Materials, Inc.	SUPERGUN	87189379 09/30/2016	5938368 12/17/2019
9.	CMC Materials, Inc.	UNI-SEAL	87189370 09/30/2016	5633402 12/18/2018
10.	CMC Materials, Inc.	AUSCILLATER	87189352 09/30/2016	5788180 06/25/2019